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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: : Wilbur G. Catabay and Richard Schinella

Appl. No. : Division of Serial No. 09/426,056

Filed: : Herewith

Title : LOW K DIELECTRIC COMPOSITE LAYER FOR INTEGRATED CIRCUIT STRUCTURE WHICH PROVIDES VOID-FREE LOW K DIELECTRIC MATERIAL BETWEEN METAL LINES WHILE MITIGATING VIA POISONING

Grp./ A.U. : 2813

Examiner : Lisa Kilday

Docket No. : 99-102/1D

PRELIMINARY AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

Date: March 15, 2002

Please amend the accompanying divisional application as follows: